



The ECD AutoM.O.L.E.[®]Xpert3 is a truly intelligent printed circuit board profiling system which will allow you to simplify your reflow soldering

recipe generation, improve PCB yields and increase overall plant capacity.

The AutoM.O.L.E.[®]Xpert3 System will assist you in three distinct areas:

1. Thermal Profile Planning.

The AutoM.O.L.E.[®]Xpert3 System provides a unique set of software tools to help you design a robust target profile for each specific combination of solder paste, reflow oven you are utilizing, and your assembly characteristics. This robust target profile can then be distributed to each of your facilities. This procedure ensures exact replication of both process parameters and PCB quality at all of your worldwide locations.

2. Reflow Oven Set-Up

Once the robust target profile has been designed, the AutoM.O.L.E.[®]Xpert3 System will generate a recipe set-up for your reflow solder machine. By inputting simple information about the PCB, your reflow machine operator can quickly have the AutoM.O.L.E.[®]Xpert3 automatically establish reflow oven settings to achieve the target profile and ensure optimum PCB quality.

3. Continuous Profile Verification

Once your initial reflow oven settings have been established, the AutoM.O.L.E.[®]Xpert3 will quickly verify that the actual oven thermal profile matches the robust target profile. Your operator simply attaches the PCB to the new SuperM.O.L.E.[®]Xpert3 Profiler. The PCB and SuperM.O.L.E.[®]Xpert3 Profile are then run through your reflow oven. At the end of the run your operator simply places the SuperM.O.L.E.[®]Xpert3 profiler into the Xpert3 docking station which is attached to your PC. The AutoM.O.L.E.[®]Xpert3 System then automatically generates the actual thermal profile, automatically compares this profile to the target profile, and, if needed, automatically suggests new Set-Points for your oven to meet the Target Profile. The operator can then take the printout and input the settings into your oven's computer.

Changing the Way The World is Profiling

When utilizing the AutoM.O.L.E.[®]Xpert3 System, you are entering a new phase in the thermal management of your automated soldering operations. In the past, you utilized a manual profiling device to measure a PCB's thermal profile within your reflow oven and then guessed what recipe settings will optimize conditions. The new AutoM.O.L.E.[®]Xpert3 System automatically guides you through the entire process: planning of the target profile, set-up of reflow machine parameters and verification of target profile production. The bottom line: you spend less time in set-up/changeover operations; you ensure consistent PCB quality from machine to machine, plant to plant; your costs go down while your quality, yields & profitability go up.

Specifications

System Requirements

Computer: 300 MHz Pentium or equivalent, 128 MB RAM (Minimum), 50 MB free space available (minimum), RS232 Port, CD-ROM Drive, Mouse

Operating System: Windows 2000 or newer

Display: 1024 x 768 preferred
(Optional)

For Connected Oven Communications:

The oven computer must meet computer requirements above.

Not just RoHS Compatible... RoHS Compliant

AutoM.O.L.E.[®]Xpert3 System Components

Software: Profile Planner Module, Automatic Reflow Oven Set-Point Calculator Module, Automatic Target Profile Replication Module

Hardware: SuperM.O.L.E.[®]Xpert3-Ready Profiler, Xpert3 Protective Barrier with single cable TC connector, Download/Charging Station*, Set of Six Color-Coded Thermocouples

**Download Station also serves as a convenient charging station. When SuperM.O.L.E.[®]Xpert3-Ready Profiler is inserted in the Xpert Station, the Profiler automatically begins charging in preparation for the next profiling run.*

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Profiling Solutions Perfected

